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PATENT

IE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Doh et al.

Group Art Unit: 2813

Serial No.: 10/659,945

Examiner: L. Schillinger

Filed: September 10, 2003

Confirmation No.: 5066

POST THERMAL TREATMENT METHODS OF FORMING HIGH

DIELECTRIC LAYERS OVER INTERFACIAL LAYERS IN

INTEGRATED CIRCUIT DEVICES

September 2, 2005

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT

Sir:

Applicants provide the present Amendment in response to the Official Action mailed May 5, 2005. It is not believed that an extension of time and/or additional fee(s), including fees for additional claims, are required, beyond those that are otherwise provided for in documents accompanying this paper. In the event, however, that additional extensions of time are necessary to allow consideration of this paper, such an extension is hereby petitioned under 37 C.F.R. §1.136(a). Any additional fees believed to be due in connection with this paper may be charged to our Deposit Account No. 50-0220.

Amendments to the Claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 9.